

Amendments to the Claims

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

Claims 1-3 (cancelled)

4 / 4. (previously presented) The cleaning wipe of Claim 23 wherein the acetylenic diol is present in the range of 0.01% to 0.3% by weight.

5 / 5. (previously presented) The cleaning wipe of Claim 4 wherein the acetylenic diol is present in the range of 0.05% to 0.2% by weight.

6 / 6. (previously presented) The cleaning wipe of Claim 5 wherein the acetylenic diol has a vapor pressure of at least 1×10^{-4} torr at 25°C.

7 / 7. (previously presented) The cleaning wipe of Claim 6 wherein the acetylenic diol has a vapor pressure of at least 1×10^{-3} torr at 25°C.

8 / 8. (previously presented) The cleaning wipe of Claim 7 wherein the acetylenic diol is dimethyl octynediol.

9 / 9. (previously presented) The cleaning wipe of Claim 7 wherein the acetylenic diol is tetramethyl decynediol.

10. (previously presented) The cleaning wipe of Claim 4 wherein the wipe substrate is selected from the group consisting of: cotton, abaca, polyester, nylon, polyester/cellulose, rayon, polypropylene, rayon/polyester, polypropylene/cellulose, polyurethane, cotton/polyester and mixtures thereof.

11. (previously presented) The cleaning wipe of Claim 4 wherein the acetylenic diol is selected from the group consisting of: dimethyl octynediol; tetramethyl decynediol; 2,6,9,13-tetramethyl-2,12-tetradecadien-7-yne-6-9-diol; 2,6,9-trimethyl-2-decen-7-yne-6-9-diol;; 7,10-dimethyl-8-hexadecyne-7,10-diol; 2,4,7,9-tetramethyl-5-decyne-4,7-diol; 4,7-dimethyl-5-decyne-4,7-diol; 3,6-diethyl-4-octyne-3,6-diol; 2,5-dicycloprpyl-3-hexyne-2,5-diol; 2,5-diphenyl-3-hexyne-2,5-diol; 3,5-dimethyl-1-hexyn-3-ol, 2,5,8,11-tetramethyl-6-dodecyne-5,8-diol and mixtures thereof.

12. (cancelled)

12. (previously presented) The cleaning wipe of Claim 11 wherein the wipe substrate is a fibrous substrate.

13. (previously presented) The cleaning wipe of Claim 11 wherein the wipe substrate is a woven fibrous substrate.

14. (previously presented) The cleaning wipe of Claim 11 wherein the wipe substrate is a nonwoven fibrous substrate.

15 ~~16.~~ (previously presented) The cleaning wipe of Claim 11 wherein the wipe substrate is a sponge.

16 ~~17.~~ (previously presented) The cleaning wipe of Claim 11 wherein the water is high purity water.

17 ~~18.~~ (previously presented) The cleaning wipe of Claim 11 wherein the water is deionized water.

18 ~~19.~~ (previously presented) The cleaning wipe of Claim 11 wherein the water is distilled water.

1 ~~20.~~ (previously presented) A prewetted cleaning wipe for cleaning surfaces in an electronic materials fabricating area having a low volatile organic chemical content in the range of 0.001% to 0.5% by weight and low nonvolatile residue property of at least 1×10^{-4} torr at 25°C comprising; a woven fibrous polyester/cellulose wipe substrate wetted with an aqueous solution consisting essentially of high purity water selected from the group consisting of distilled water and deionized water, and from 0.001 % to 0.5% by weight of an acetylenic diol surface active agent selected from the group consisting of dimethyl octynediol, tetramethyl decynediol and mixtures thereof.

21. (cancelled)

2 ~~22.~~ (previously presented) The cleaning wipe of Claim 20 wherein the acetylenic diol surface active agent is present in an amount from 0.05% to 0.2% by weight.

~~3~~ 23. (previously presented) In a cleaning wipe for use in cleaning an electronics fabrication industry clean room comprising a wipe substrate wetted with a cleaning solution, the improvement which resides in a cleaning wipe having low volatile organic chemical and low nonvolatile residue properties comprising a wipe substrate wetted with a solution consisting essentially of water and from 0.001% to 0.5% by weight of an acetylenic diol.

~~cancelled~~ 24. (New) In a process for cleaning surfaces in an electronics fabrication cleanroom wherein the surfaces are contacted with a cleaning wipe and contaminates removed from said surfaces, the improvement which comprises:

utilizing a cleaning wipe consisting essentially of a wipe substrate impregnated with a solution consisting essentially of water and from 0.001% to 0.5% by weight of an acetylenic diol.

~~cancelled~~ 25. (New) The process of Claim 24 wherein the acetylenic diol is selected from the group consisting of dimethyl octynediol and tetramethyl decynediol.